



LOWBOARD 15 INSTALL GUIDE IG UFH 01.1

Installation guide for LowBoard 15

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STORAGE & FLOOR PREPARATION

NOTE: If it is necessary to store the system once you have taken delivery, ensure it is kept in the following conditions:

- A dry, weather tight area
- Out of direct sunlight
- Away from sharp objects or chemical spillages
- All chipboard, woodboard or plywood must be stacked horizontally and raised off the ground. It must not be exposed to moisture or high humidity.

Ensure existing slab/floor deck meets at least SR2 (5mm deviation in 2m) requirements for floor regularity (BS8204) and preferably SR1 (3mm deviation in 2m).

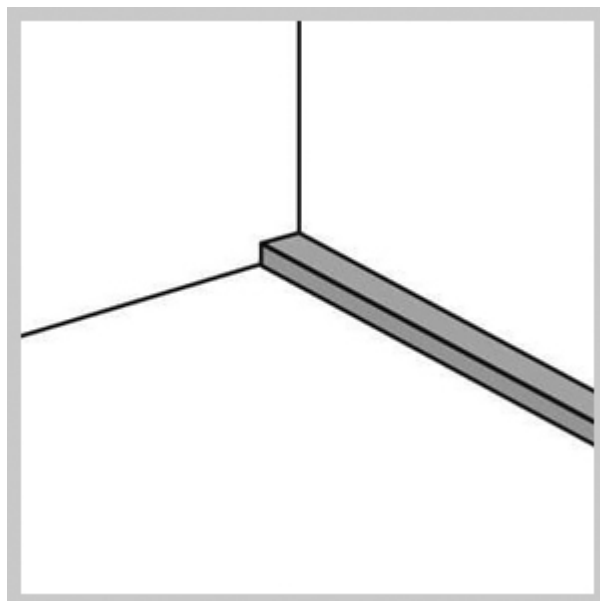
NOTE: The floor finish company may have their own requirements which take precedent.

NOTE: Any undulations in the floor will transfer through the LowBoard. If laying on a solid floor, a thin layer of non-compressive insulation/insulative matting can be laid prior to fitting LowBoard 15 to provide some resistance when layering over a floor. (Not applicable when laying tiles or decorative finishes see note above)

STAGE 2

Where flows and returns are planned to run along a wall, lay a 50mm wide x 15mm high batten or LowBoard 15 offcut against the wall.

NOTE: When working with any wood or insulation based products, dust and particles become airborne and pose a hazard to health. This is particularly relevant when machining, cutting or routing. Please follow the relevant guidelines in the product safety datasheets (available on request) on reducing the risk of dust inhalation.



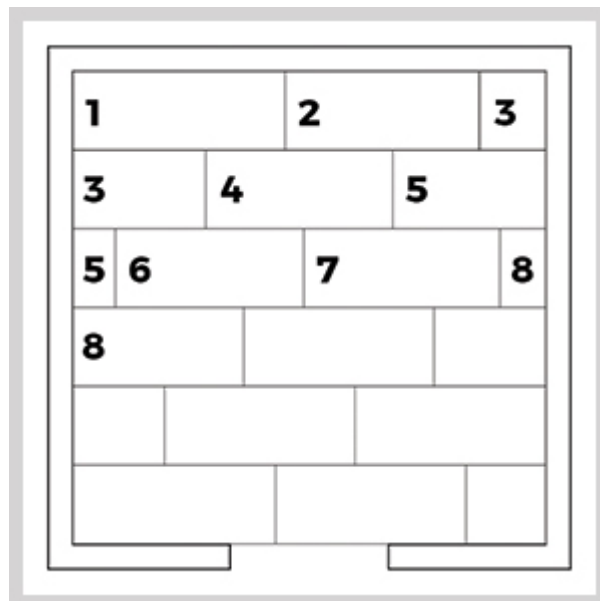
STAGE 3

Starting from one corner, lay the first LowBoard 15 panel.

Leave the following gaps when laying the panels:

- 75mm gap between the panel and the batten
- 10mm gap between the panel and the wall (using a spacer)

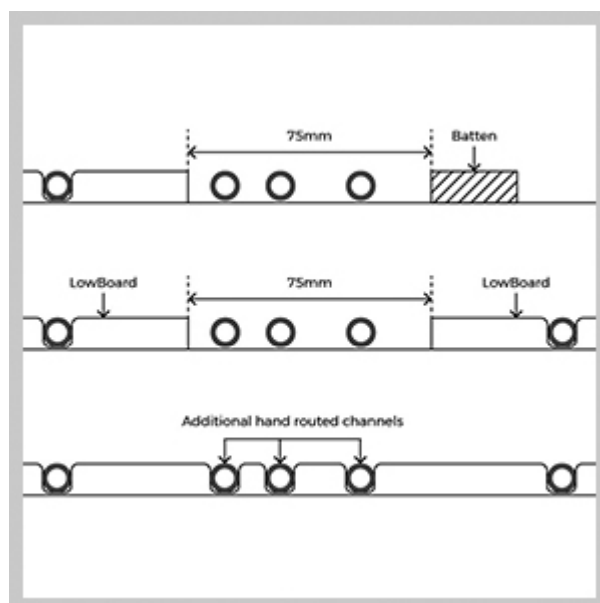
Continue laying the LowBoard panels across the floor in a 'run'. Use can the off cuts to start the next run of panels providing there is a return loop at the end of the run.



STAGE 4

If there are multiple flows and returns that cannot be accommodated in the pre-routed channel (such as the approach to the manifold), use one of the following methods:

- Lay 50mm wide x 15mm high battens with a 75mm gap between battens
- Leave a 75mm gap between LowBoard 15 panels
- Hand rout the required 12mm channels in the LowBoard panels

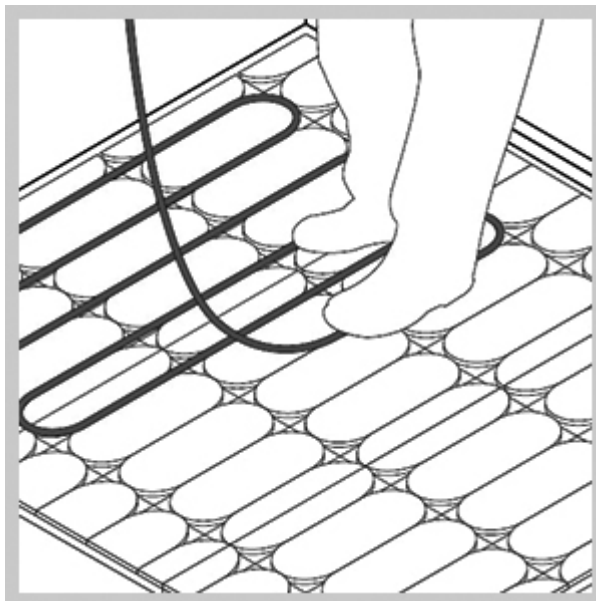


STAGE 5

Starting at the manifold and referring to the OMNIE CAD design, insert the pipe into the LowBoard 15 panels by piercing the foil layer. Continue laying the pipe until all circuits have been laid.

The minimum temperature for laying the pipe should be +5°C.

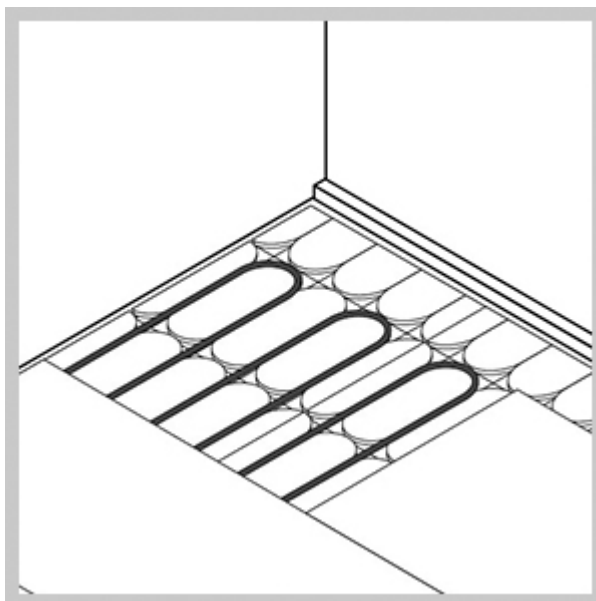
NOTE: If the pipe work is kinked during the installation, the coil must be replaced or the pipe repaired with an OMNIE connector (if possible) and then pressure tested. No connections should be made unless fully accessible following the completion of the finished floor.



STAGE 6

Once the panels and pipe have been laid, the circuits should be hydraulically pressure tested and kept under pressure while the floor finish and/or covering ply or similar are laid.

Please note – do not use adhesives directly on the LowBoard panel, any floor coverings that are fixed down must be mechanically fixed and not bonded.



A QUICK GUIDE TO FILLING THE SYSTEM

1. If the manifold is being used to pressure test all circuits at once, close both primary isolation valves.
2. Connect a pressure tester to the drain valve, vent the system of air and increase the pressure to 6 bar.
3. Once at this pressure, leave for 60 minutes. If the pressure has dropped examine the pipework. It may be necessary to pressure test individual circuits to determine if there has been damage to the pipe.
4. If the pressure is maintained and passes the test, record the results on the pressure test certificate. Have the test witnessed and certified by a third party.
5. Maintain this test pressure whilst the floor finish and/or covering ply (or similar) is being laid.

SEE MANIFOLD INSTALLATION GUIDE (DOCUMENT CODE: IG UFH 17) FOR FULL INSTRUCTIONS

NOTES ON FLOATING FLOORS

The floor deck or finish should be timber or timber composite with tongued and grooved edges. LowBoard 15 panels should butt tightly together with no gaps. The LowBoard 15 panels should be laid in a brick pattern so that joints are not co-incident with the previous row or line up with joints in the floor deck above.

During the initial heat up, the mixing valve should be set to supply temperature of between 20°C and 25°C which needs to be maintained for at least 3 days. After this period, the flow temperature can then be increased to the design maximum and should be held for a further 4 days to complete the process.

NOTE: Always refer to the flooring manufacturer's instructions.

